



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IFX25001TF V50	<b>Issued</b>	24. February 2022
<b>MA#</b>	MA005700931		
<b>Package</b>	PG-TO252-3-11	<b>Weight*</b>	379.77 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.179	0.84	0.84	8371	8371
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		170	
	non noble metal	iron	7439-89-6	0.215	0.06		567	
	non noble metal	copper	7440-50-8	215.017	56.61	56.69	566169	566906
wire	non noble metal	aluminium	7429-90-5	0.176	0.05	0.05	463	463
encapsulation	organic material	carbon black	1333-86-4	0.267	0.07		702	
	plastics	epoxy resin	-	12.261	3.23		32286	
	inorganic material	silicondioxide	60676-86-0	120.747	31.79	35.09	317945	350933
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9848	9848
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	239	240
solder	non noble metal	tin	7440-31-5	0.096	0.03		254	
	noble metal	silver	7440-22-4	0.120	0.03		317	
	non noble metal	lead	7439-92-1	4.597	1.21	1.27	12105	12676
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			15	
	non noble metal	iron	7439-89-6	0.019	0.01		51	
	non noble metal	copper	7440-50-8	19.177	5.05	5.06	50497	50563
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com